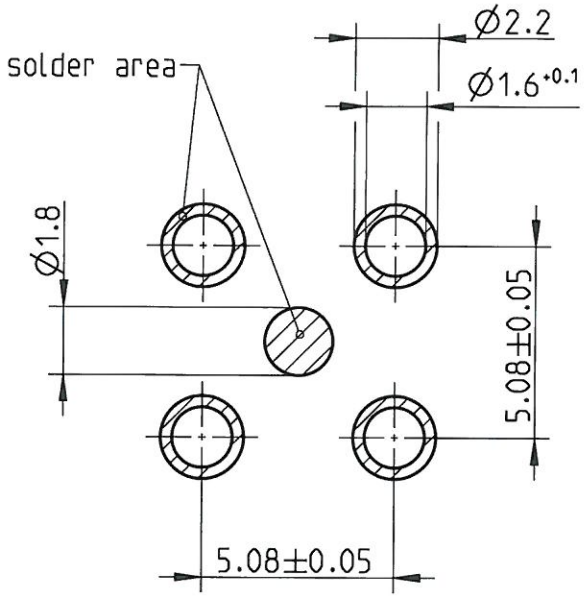
Leiterplatten-Layout
PCB layout
B 115a



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.
Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.
In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formblatt: TFC_FB_05_PE_A4_Einzelteil
Pfad: i:\Pro-Config\Rahmen\
Datei: A4_LANDSCAPE_EDB.FRM
Version: 1.2

Dimensions in mm

ISO-Projektion Methode E

c00	09-0794	A_Nobis	19.11.2009
b00	06-0194	S_Krautenbac	19.04.2006
a00	04-s296	A_Nobis	13.08.2004
rev.	change-no	name	date

Rosenberger
Hochfrequenztechnik
84526 Tittmoning
Pro/ENGINEER

general tolerance
ISO 2768 m-H
RN 006-01 dimensions <0,5 and symmetry

	date	name
drawn	13.08.2004	A_Nobis
check.	19.11.09	
appr.	19.11.2009	
dimensioning incl. finish		

distribution to:	FE	AZ	QSM	RMT	.
	X	.	.	.	.

scale: 5:1
weight[g]:
surface[mm²]:
material:

title:
Leiterplatten-Layout
PCB layout

drawing-no..: MB_115A
sheet: 1
of: 1

remarks: .